

SEMICONDUCTOR DEVICE

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Classification:

- **International:** *H01L23/34; H01L23/50; H05K3/30; H05K3/34; H01L23/34; H01L23/48; H05K3/30; H05K3/34; (IPC1-7): H01L23/34; H01L23/50*

- **European:**

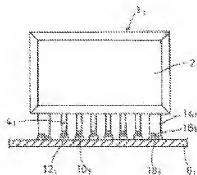
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Abstract of **JP 5036888 (A)**

PURPOSE:To enable a semiconductor device which is mounted upright on a board to be more enhanced in mounting density than usual.

CONSTITUTION:A support 141 electrically separate from outer leads 41 is erected extending outward from a resin-sealed part 21, and an outer fixing part 161 is provided to the end of the support 141.



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Also published as:

JP2612114 (B2)